

IN THE SPECIFICATION:

Please amend the specification as follows:

Paragraph beginning on page 3, at prenumbered line 9, has been amended as follows:

Fig. 3 is a cross-section view illustrating the multi-chip package combining wire-bonding and flip-chip configuration across ~~3-3~~ I-I line of Fig. 1 according to the first embodiment of the present invention.

Paragraph beginning on page 3, at prenumbered line 23, has been amended as follows:

According to a first embodiment of the present invention, a multi-chip package 100 combining wire-bonding and flip-chip configuration is showed in Fig. 1, 2 and 3. Fig. 1 is a top view illustrating the multi-chip package 100. Fig. 2 is a cross-section view illustrating the multi-chip package 100 before mounting a flip-chip type electrical device 140. Fig. 3 is a cross-section view illustrating the multi-chip package 100 across ~~3-3~~ I-I line of Fig. 1. The multi-chip package 100 comprises a substrate 110, at least a wire-bonding chip 120, a molding compound 130 and at least a flip-chip type electrical device 140.

Paragraph beginning on page 8, at prenumbered line 10, has been amended as follows:

Referring to Fig. 7, another multi-chip package combining wire-bonding and flip-chip configuration is disclosed according to the forth embodiment of the present invention. The multi-chip package comprises some components, such as a substrate 310 with a plurality of contact pads, a molding compound 330 which seals wire-bonding chips and a flip-chip type electrical device 320, which are the same as the third embodiment of the present invention and use the same figure number. The molding compound 330 is selectively formed on the upper surface 311 of the substrate 310 by molding process. The molding compound 330 has a recession 331 and symmetric extensions 332 from two sides of the recession 331. The molding

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compound 330 forms an indentation ~~333~~ 334 at the connecting portion of the symmetric extensions 332 to achieve reducing the warpage of the substrate 310.